# **4-Bit Full Adder**

The MC14008B 4-bit full adder is constructed with MOS P-Channel and N-Channel enhancement mode devices in a single monolithic structure. This device consists of four full adders with fast internal look-ahead carry output. It is useful in binary addition and other arithmetic applications. The fast parallel carry output bit allows high-speed operation when used with other adders in a system.

#### **Features**

- Look–Ahead Carry Output
- Diode Protection on All Inputs
- All Outputs Buffered
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–Power TTL Loads or One Low–Power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4008B
- This Device is Pb-Free and is RoHS Compliant

## MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: "D/DW" Package: -7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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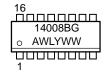


SOIC-16 D SUFFIX CASE 751B

#### **PIN ASSIGNMENT**

A4 [	1 ●		V <sub>DD</sub>
B3 [	2	15	] B4
A3 [	3	14	C <sub>out</sub>
B2 [	4	13	] S4
A2 [	5	12	] S3
B1 [	6	11	] S2
A1 [	7	10	] S1
V <sub>SS</sub> [	8	9	C <sub>in</sub>

## **MARKING DIAGRAM**



A = Assembly Location

 $\begin{array}{ll} \text{WL, L} &= \text{Wafer Lot} \\ \text{YY, Y} &= \text{Year} \\ \text{WW, W} &= \text{Work Week} \\ \text{G} &= \text{Pb-Free Indicator} \end{array}$ 

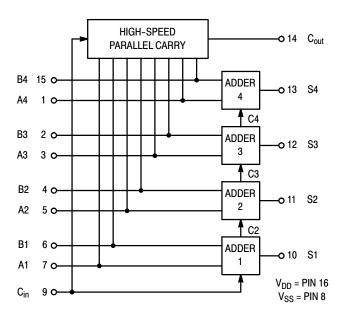
#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

TRUTH TABLE (One Stage)

C <sub>in</sub>	В	Α	C <sub>out</sub>	S
0	0	0	0	0
0	0	1	0	1
0	1	0	0	1
0	1	1	1	0
1	0	0	0	1
1	0	1	1	0
1	1	0	1	0
1	1	1	1	1

#### **BLOCK DIAGRAM**



## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC14008BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

				-55°C 25°C		125	5°C				
Characteristic		Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	V <sub>OL</sub>	5.0 10 15		0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or $V_{DD}$	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95		4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95		Vdc
Input Voltage ( $V_O = 4.5 \text{ or } 0.5 \text{ Vdc}$ ) ( $V_O = 9.0 \text{ or } 1.0 \text{ Vdc}$ ) ( $V_O = 13.5 \text{ or } 1.5 \text{ Vdc}$ )	"0" Level	V <sub>IL</sub>	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	I <sub>OH</sub>	5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	- - -	-2.4 -0.51 -1.3 -3.4	-4.2 -0.88 -2.25 -8.8	- - -	-1.7 -0.36 -0.9 -2.4	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		I <sub>in</sub>	15	_	±0.1	_	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	-	-	-	-	5.0	7.5	_	-	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20		150 300 600	μAdc
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)		I <sub>T</sub>	5.0 10 15			$I_T = (3)$	1.7 μΑ/kHz) f 3.4 μΑ/kHz) f 5.0 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

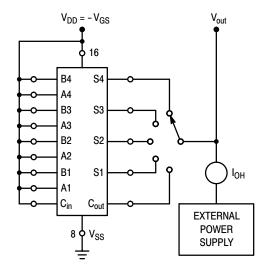
where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.005.

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

# **SWITCHING CHARACTERISTICS** (Note 5) ( $C_L = 50 \text{ pF}, T_A = 25^{\circ}C$ )

Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time	t <sub>TLH</sub> ,					ns
$t_{TLH}$ , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$	t <sub>THL</sub>	5.0	_	100	200	
$t_{TLH}$ , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$		10	_	50	100	
$t_{TLH}$ , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$		15	_	40	80	
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>					ns
Sum in to Sum Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 315 \text{ ns}$		5.0	_	400	800	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 127 \text{ ns}$		10	_	160	320	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 90 \text{ ns}$		15	_	115	230	
Sum In to Carry Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 220 \text{ ns}$		5.0	_	305	610	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 112 \text{ ns}$		10	_	145	290	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 85 \text{ ns}$		15	_	110	220	
Carry In to Sum Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 290 \text{ ns}$		5.0	_	375	750	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 122 \text{ ns}$		10	_	155	310	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 90 \text{ ns}$		15	_	115	230	
Carry In to Carry Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 85 \text{ ns}$		5.0	_	170	340	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$		10	_	75	150	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 30 \text{ ns}$		15	_	55	110	

- 5. The formulas given are for the typical characteristics only at 25°C.6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



**Figure 1. Typical Source Current** Characteristics Test Circuit

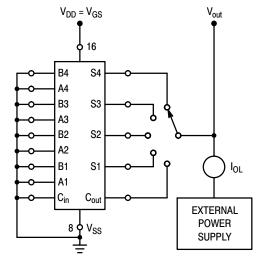


Figure 2. Typical Sink Current **Characteristics Test Circuit** 

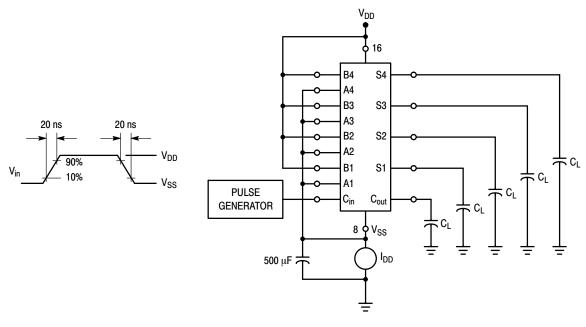


Figure 3. Dynamic Power Dissipation Test Circuit and Waveform

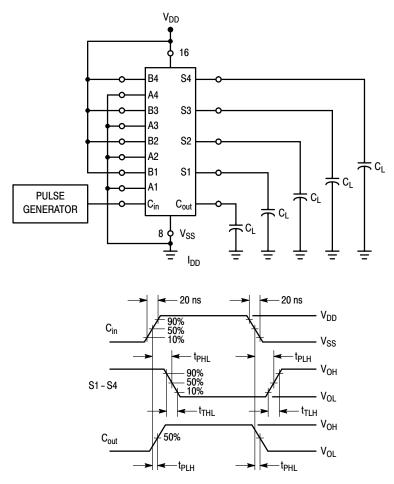


Figure 4. Switching Time Test Circuit and Waveforms

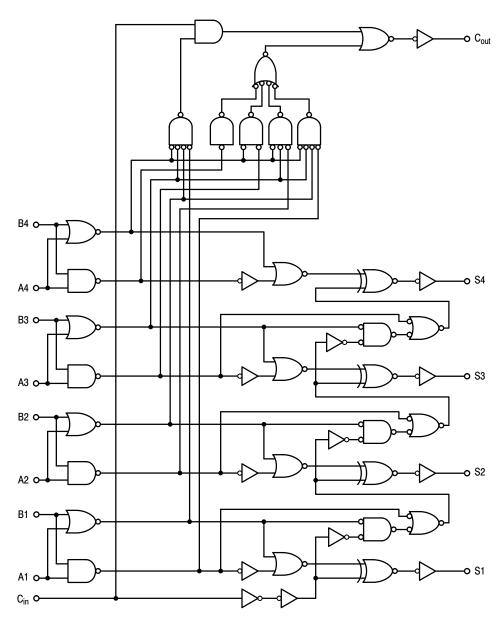
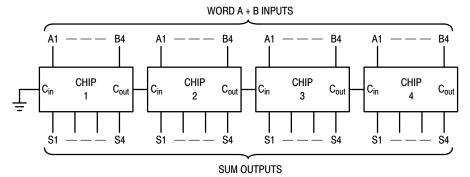


Figure 5. Logic Diagram

## **TYPICAL APPLICATION**



Calculation of 16-bit adder speed:

 $t_P$  total =  $t_P$  (Sum to Carry) +  $t_P$  (Carry to Sum) + 2  $t_P$  (Carry to Carry) The guaranteed 16-bit adder speed at 10 V, 25°C,  $C_L$  = 50 pF is:

 $t_p \text{ total} = 290 + 310 + 300 = 900 \text{ ns}$ 

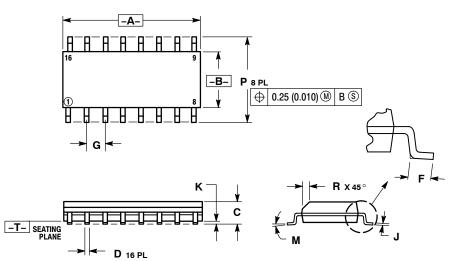
Figure 6. Using the MC14008B in a 16-Bit Adder Configuration





#### SOIC-16 CASE 751B-05 **ISSUE K**

**DATE 29 DEC 2006** 



⊕ 0.25 (0.010) M T B S A S

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD ENGREPHING.

- PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION.
  SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D
  DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
7	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:		
	COLLECTOR	PIN 1.	CATHODE	PIN 1.		PIN 1.	COLLECTOR, DYE #	1
2.	BASE	2.	ANODE	2.		2.	COLLECTOR, #1	
3.	EMITTER	3.	NO CONNECTION	3.	EMITTER, #1	3.	COLLECTOR, #2	
4.	NO CONNECTION	4.	CATHODE	4.	COLLECTOR, #1	4.	COLLECTOR, #2	
5.	EMITTER	5.	CATHODE	5.	COLLECTOR, #2	5.	COLLECTOR, #3	
6.	BASE	6.	NO CONNECTION	6.	BASE, #2	6.	COLLECTOR, #3	
7.	COLLECTOR	7.	ANODE	7.	EMITTER, #2	7.	COLLECTOR, #4	
8.	COLLECTOR	8.	CATHODE	8.	COLLECTOR, #2	8.	COLLECTOR, #4	
9.	BASE	9.	CATHODE	9.	COLLECTOR, #3	9.	BASE, #4	
10.	EMITTER	10.	ANODE	10.	BASE, #3	10.	EMITTER, #4	
11.	NO CONNECTION	11.	NO CONNECTION	11.	EMITTER, #3	11.	BASE, #3	
12.	EMITTER	12.		12.	COLLECTOR, #3	12.	EMITTER, #3	
13.	BASE	13.		13.		13.	BASE, #2	RECOMMENDED
14.	COLLECTOR	14.	NO CONNECTION	14.		14.	EMITTER, #2	SOLDERING FOOTPRINT*
15.	EMITTER	15.	ANODE	15.	EMITTER, #4	15.	BASE, #1	
16.	COLLECTOR	16.	CATHODE	16.	COLLECTOR, #4	16.	EMITTER, #1	8X
								<b>←</b> 6.40 <b>→</b>
STYLE 5:		STYLE 6:		STYLE 7:				1
PIN 1.	DRAIN, DYE #1		CATHODE		SOURCE N-CH			16X 1.12 < ➤
2.	DRAIN, #1	2.	CATHODE	2.	COMMON DRAIN (OUTPU	T)		
3.	DRAIN, #2	3.	CATHODE	3.	COMMON DRAIN (OUTPU			1 16
4.	DRAIN, #2	4.	CATHODE	4.	GATE P-CH	,	1	
5.	DRAIN, #3	5.	CATHODE	5.	COMMON DRAIN (OUTPU	T)		
6.	DRAIN, #3	6.	CATHODE	6.	COMMON DRAIN (OUTPU	T)	16X	
7.	DRAIN, #4	7.		7.	COMMON DRAIN (OUTPU	T)	0.58 -	
8.	DRAIN, #4	8.	CATHODE	8.	SOURCE P-CH			
9.	GATE, #4	9.	ANODE	9.	SOURCE P-CH			
10.	SOURCE, #4	10.	ANODE	10.	COMMON DRAIN (OUTPU		-	<del></del>
11.	GATE, #3	11.	ANODE	11.				
12.	SOURCE, #3	12.	ANODE	12.	COMMON DRAIN (OUTPU	T)		
13.	GATE, #2	13.	ANODE	13.	GATE N-CH			
14.	SOURCE, #2		ANODE	14.				
15.	GATE, #1	15.	ANODE	15.	COMMON DRAIN (OUTPU	T)		PITCH
16.	SOURCE, #1	16.	ANODE	16.	SOURCE N-CH			
								□□18   9 <del>1 = 1                               </del>
								DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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